

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4130	"257"/\$.ccls. and (semiconductor near3 module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/12/07 11:31
L2	3663	"257"/\$.ccls. and (semiconductor near3 module) and ((circuit adj board) or board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/12/07 11:31
L3	3389	"257"/\$.ccls. and (semiconductor near3 module) and ((circuit adj board) or board or substrate) and (chip or IC or component or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/12/07 11:32
L4	2153	"257"/\$.ccls. and (semiconductor near3 module) and ((circuit adj board) or board or substrate) and (chip or IC or component or die) and wires	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/12/07 11:32
L5	1402	"257"/\$.ccls. and (semiconductor near3 module) and ((circuit adj board) or board or substrate) and (chip or IC or component or die) and wires and vias	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/12/07 11:33
L6	246	"257"/\$.ccls. and (semiconductor near3 module) and ((circuit adj board) or board or substrate) and (chip or IC or component or die) and wires and vias and recess	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/12/07 11:33